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TUESDAY POSTER PAPERS

Tuesday, August 7, 2012

Tue AM, Poster Paper

Meet and Greet Authors 10:30 am to 12:00pm Tuesday.

TUESDAY TECHNICAL PAPERS

Tuesday, August 7, 2012

TU-AM-1 TC1 EMC Management

Chair: Doug Kramer, ETS-Lindgren

TU-AM-2 TC10 Modeling of Interconnects

Chair: Francesco de Paulis, University of L'Aquila

8:30 am **Semi-Automatic Copper Foil Surface Roughness Detection from PCB Microsection Images** 132
Soumya De *(Missouri University of Science and Technology, Rolla, MO, US);* Aleksandr Gafarov *(Missouri University of Science and Technology, Rolla, MO, US);* Marina Y. Koledintseva *(Missouri University of Science and Technology, Rolla, MO, US);* R. Joe Stanley *(Missouri University of Science and Technology, Rolla, MO, US);* James L. Drewniak *(Missouri University of Science and Technology, Rolla, MO, US);* Scott Hinaga *(Cisco Systems Inc., San Jose, CA, US)*

9:00 am **PCB Conductor Surface Roughness as a Layer with Effective Material Parameters** 138
Marina Y. Koledintseva *(Missouri University of Science and Technology, Rolla, MO, US);* Alexander G. Razmadze *(Missouri University of Science and Technology, Rolla, MO, US);* Aleksandr Y. Gafarov *(Missouri University of Science and Technology, Rolla, MO, US);* Soumya De *(Missouri University of Science and Technology, Rolla, MO, US);* James L. Drewniak *(Missouri University of Science and Technology, Rolla, MO, US);* Scott Hinaga *(Cisco Systems, Inc., San Jose, CA, US)*
** Nominated for Best Symposium Paper Award*

9:30 am **Analysis of Common-Mode Noise on On-Chip Differential Lines through Stochastic Modeling of Parameter Variability** 144
Dries Vande Ginste *(Ghent University, Gent, BE);* Daniël De Zutter *(Ghent University, Gent, BE);* Dirk Deschrijver *(Ghent University, Gent, BE);* Tom Dhaene *(Ghent University, Gent, BE);* Paolo Manfredi *(Politecnico di Torino, Torino, IT);* Flavio Canavero *(Politecnico di Torino, Torino, IT)*

TU-AM-3 TC9 Numerical Investigation of Reverb Chambers

Chair: Vignesh Rajamani, Oklahoma State University

9:00 am **Numerical Study of Currents Induced on a Partially Shielded Wire within an Ideal Reverberation Test Chamber** 150
Endegena Assefa *(Oklahoma State University, Stillwater, OK, US);* James C. West *(Oklahoma State University, Stillwater, OK, US);* Vignesh Rajamani *(Oklahoma State University, Stillwater, OK, US);* Charles F. Bunting *(Oklahoma State University, Stillwater, OK, US)*

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Giacomo Bosco *(Università Politecnica delle Marche, Ancona, IT);* Cesare Picciani *(Università Politecnica delle Marche, Ancona, IT);* Valter Mariani Primiani *(Università Politecnica delle Marche, Ancona, IT);* Franco Moglie *(Università Politecnica delle Marche, Ancona, IT)*

TU-AM-4 SC3 Transportation Systems

Chair: Mark Steffka, University of Michigan
Co-Chair: Jeremy Campbell

9:00 am **Automotive AM-Band Radiated Emission Mitigation Techniques, A Practical Approach** 162
Cyrous Rostamzadeh *(Robert Bosch LLC, Plymouth, MI, US);* Flavio Canavero *(Politecnico di Torino, Torino, IT);* Feraydune Kashefi *(Azad University, Shabestar, IR);* Mehdi Darbandi *(Tehran University, Tehran, IR)*

TU-PM-1 SS TC10 Channel Characterization and Modeling for High-Speed Signaling

Chair: Jianmin Zhang, Cisco Systems, Inc
Co-Chair: Ye Chunfei, Intel

TU-PM-2 TC2 Reverb and TEM

Chair: Diane Kempf, US Navy
Co-Chair: Galen Koepke, NIST

TU-PM-3 TC9 Practical Application of Numerical Modeling

Chair: Todd Hubing, Clemson University

TU-PM-4 TC4 Radiated Emissions

Chair: Philip Keebler, Electric Power Research Institute
Co-Chair: Michael Evans, Student

TU-PM-5 TC5 High Power Electromagnetics (Including IEMI and ESD)

Chair: Bill Radasky, Metatech Corporation
Co-Chair: Michael McInerney, US Army Corp of Engineers

WEDNESDAY TECHNICAL PAPERS

Wednesday, August 8, 2012

WED-AM-1 SC1 Smart Grid

Chair: Don Heirman, Don HEIRMAN Consultants

WED-AM-2 TC4 Emissions Prediction and Testing

Chair: Michael Evans, Student
Co-Chair: Philip Keebler, Electric Power Research Institute

WED-AM-3 TC9 Modeling of EM Pulses

Chair: Wen-Yan Yin, Shanghai Jiao Tong University

WED-AM-4 TC11 Nano Technology

Chair: Marina Koledintseva, Missouri University of Science and Technology

WED-PM-1 SS TC 11 Nanotechnology for EMC

Chair: Marina Koledintseva, Missouri University of Science and Technology
Co-Chair: Alessio Tamburrano, Sapienza University of Rome

WED-PM-2 TC2 Emissions Measurements

Chair: Don Heirman, Don HEIRMAN Consultants
Co-Chair: H. Robert Hofmann, Hofmann EMC Engineering

WED-PM-3 TC9 Advances in Modeling Techniques

Chair: Albert Ruehli, Missouri University of Science and Technology
Co-Chair: Lijun Jiang, University of Hong Kong

WED-PM-4 TC10 Signal Integrity

Chair: Francesco Ferranti, Ghent University
Co-Chair: Antonio Ciccomancini, CST of America

THURSDAY TECHNICAL PAPERS

Thursday, August 9, 2012

TH-AM-1 SS TC6 Evolving Trends in Spectrum Management and Engineering

Chair: Larry Cohen, Naval Research Laboratory
Co-Chair: Bob Johnk, Institute for Telecommunication Sciences (NTIA/ITS)

TH-AM-2 TC9 Field Transformation

Chair: Alan Roden

TH-AM-3 TC4 Shielding Analysis and Application

Chair: John Kraemer
Co-Chair: Phil Berger, John Deere Tractor Co.

TH-AM-4 TC2 Shielding

Chair: Bill Radasky, Metatech Corporation

TH-PM-1 SS TC9 Model Validation with FSV

Chair: Jianmin Zhang, Cisco Systems, Inc
Co-Chair: Bruce Archambeault, IBM Corporation

TH-PM-2 TC2 Antennas

Chair: Dave Arnett, Hewlett Packard
Co-Chair: H. Robert Hofmann, Hofmann EMC Engineering

TH-PM-3 TC3 EM Environment

Chair: Fred Heather

TH-PM-4 TC7 Low Frequency EMC Methods and Applications Including Power Quality

Chair: Magnus Olofsson, Elforsk - Swedish Electrical Utilities' R & D Company
Co-Chair: Dave Thomas, University of Nottingham

TH-PM-5 TC5 Information Leakage

Chair: Yuichi Hayashi, Tohoku University
Co-Chair: William Price, Boeing